



Summary of High Reliability Test

Test Item	Test Condition	Reference Document	Test Qty'	Test Result
Solderability	Dip in flux Time=5~10 sec. Temperature of solder pot = 245±5 , Time=5~10sec.	MIL-STD-750D METHOD 2026.1	22	Pass
Soldering Heat	Temperature of solder pot = 260±5 , Time=10~12sec.	MIL-STD-750D METHOD 2031.2	22	Pass
Temperature Cycle	Tstg(Min.) to Tstg(Max.) dwelled for 30 min and transfer time not exceed 1min; 20 cycles.	MIL-STD-750D METHOD 1051.5	22	Pass
Thermal Shock Test	Ta1=100 , Time=10min then Ta2=0 , Time=10min for 20 cycles, transfer time must not exceed 5 sec.	MIL-STD-750D Method 1056.7	22	Pass
Steady State Operation Life Test	I=Io Time=168 hrs.	MIL-STD-750D Method 1027.3	22	Pass
High Temperature Reverse Bias Life	$V_R=80\%V_{RRM}$ Ta=Tstg(Max.) ±5 Testing Time=168 hrs.	MIL-STD-750D Method 1038.3	22	Pass
Intermittent Forward Operation Life	IF=Io Power ON 1.5hrs/OFF 0.5hrs Testing Time : 500 Cycles.	MIL-STD-750D Method 1036.3	22	Pass
Pressure Cooker Test	Ta=121 Pressure=15 Psi Time=12 hrs	MIL-STD-19500E Appendix C	22	Pass
High Temperature Storage Life	Ta=T _{STG} MAX. Time=168 hrs	MIL-STD-750D Method 1031.5	22	Pass
Moisture Resistance	Temp 25 up to 60 keep for 3 hrs, then down to 25 and repeat once again (RH=90~100%). Total 10 cycles, a subcycle shall be performed. Subcycle condition: -10 , 3hrs minimum	MIL-STD-750D Method 1021.2	22	Pass
Sample Size: 22 Acceptance: 0/22				